

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Masafumi HASHIMOTO, et al.

Serial No.: 10/591,749

Group Art Unit: 1794

Filed: September 6, 2006

Examiner: Monique R. Jackson

For: ADHESION-ENHANCED POLYIMIDE FILM, PROCESS

FOR ITS PRODUCTION, AND LAMINATED BODY

DECLARATION UNDER 37 C.F.R. 1.132

Commissioner for Patents

Alexandria, VA 22313

Sir:

I, Takeshi UEKIDO, c/o Ube Chemical Factory, Ube Industries, Ltd., 1976-96, Oaza Kogushi, Ube-shi, Yamaguchi 755-8633, Japan do hereby declare:

That I am a co-inventor of the invention in the above-identified U.S. application (hereinafter referred to as "present invention" for brevity) and hence I am fully familiar therewith, and I have read and am fully familiar

with the art cited against the claims of the above-identified U.S. application (hereinafter referred to as "present application for brevity);

That, in conjunction with the other co-inventors, I carried out the working examples including comparative examples set forth in the specification of the present application, and the results were as set forth therein;

That, to show that the present invention should be patentably distinguished from the art of Japanese Unexamined Patent Publication No. 2000-043211 which I have recently noticed, I carried out the following comparative working.

Comparative Working

A polyimide film and laminated body were obtained in the same manner as Example 6 of the present application, except that the thin-layer polyimide (B) precursor solution composition obtained in Reference Example 2-3 was used as the thin-layer polyimide (B) precursor solution composition and the thin-layer side of the polyimide film was laminated (180°C, 20 kgf/cm²) with a copper foil (35 μm, HPP-SP35-E by Hitachi Cable, Ltd.). The obtained peel strength was 1,100 N/m.

For comparison, the above-mentioned procedure was repeated except that γ -phenylaminopropyltrimethoxysilane was not used in Reference Example 2-3. The obtained peel strength was 280 N/m.

I, the undersigned declarant, declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and; further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001, of Title 18, of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Signed this 29th day of June , 2010

Takeshi Uekido

Takeshi Uekido